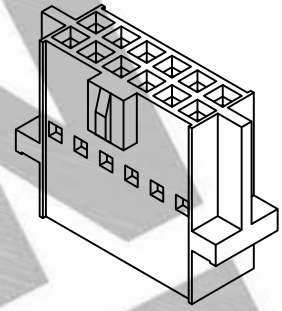
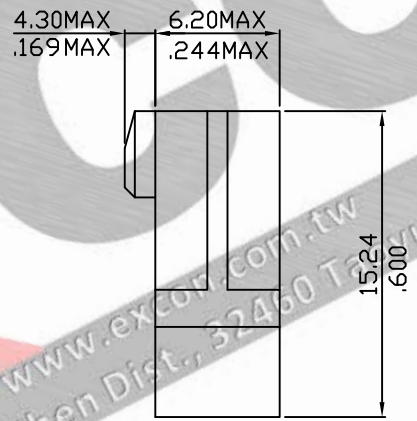
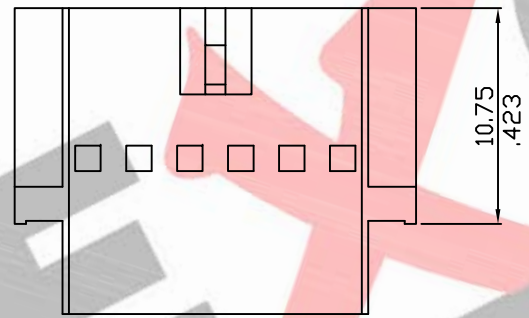
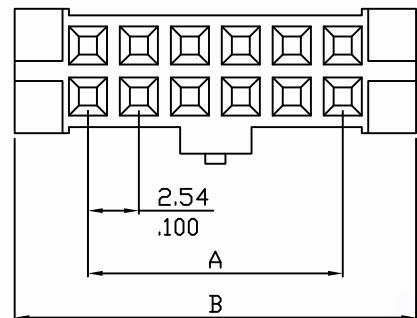


PART NO. 8823xxHC298
 DWG NO. C8823HC



Part No.	Circuits	Dim A	Dim B
882308HC298	8	7.62(.300)	10.16(.400)
882310HC298	10	10.16(.400)	12.70(.500)
882312HC298	12	12.70(.500)	15.24(.600)
882314HC298	14	15.24(.600)	17.78(.700)
882316HC298	16	17.78(.700)	20.32(.800)
882318HC298	18	20.32(.800)	22.86(.900)
882326HC298	26	30.48(1.200)	33.02(1.300)
882334HC298	34	40.64(1.600)	43.18(1.700)
882340HC298	40	48.26(1.900)	50.80(2.000)
882350HC298	50	60.96(2.400)	63.50(2.500)
882360HC298	60	73.66(2.900)	76.20(3.000)
882364HC298	64	78.74(3.100)	81.28(3.200)

NOTE:

1. Wafer Material: PPO , PBT
2. Insulation resistance: 1000M ohm/min.
3. Withstand voltage: 1000V AC/minute.
4. Current rating: 3A AC/DC.
5. Voltage rating: 250V AC/DC

UNLESS OTHERWISE SPECIFIED TOLERANCES			
3 PLACE ±0.5 ±0.10			
2 PLACE ±1.5 ±0.25			
1 PLACE ±2.0 ±0.50			
ANGLE DIM			
REV.	REVISION		DIS DATE
SCALE	REV.	PAGE:	UNIT mm
2/1	A	1	THIRD ANGLE PROJECTION

EXCON
 EXCON TECHNOLOGY COMPANY

PART.NO
 8823xxHC298

